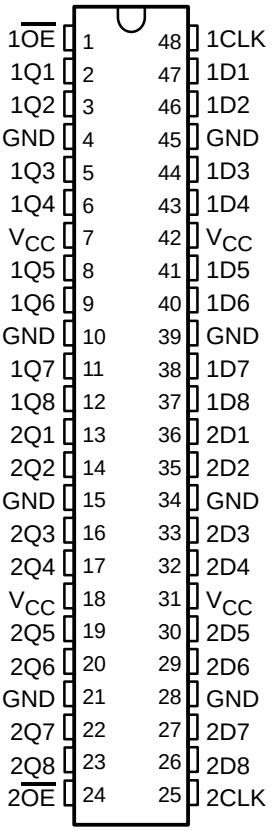
- **Members of the Texas Instruments *Widebus*™ Family**
- **3-State True Outputs**
- **Full Parallel Access for Loading**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings**

54AC16374 . . . WD PACKAGE
74AC16374 . . . DL PACKAGE
(TOP VIEW)



description

The ’AC16374 are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The ’AC16374 can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

$\overline{OE}$ does not affect the internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

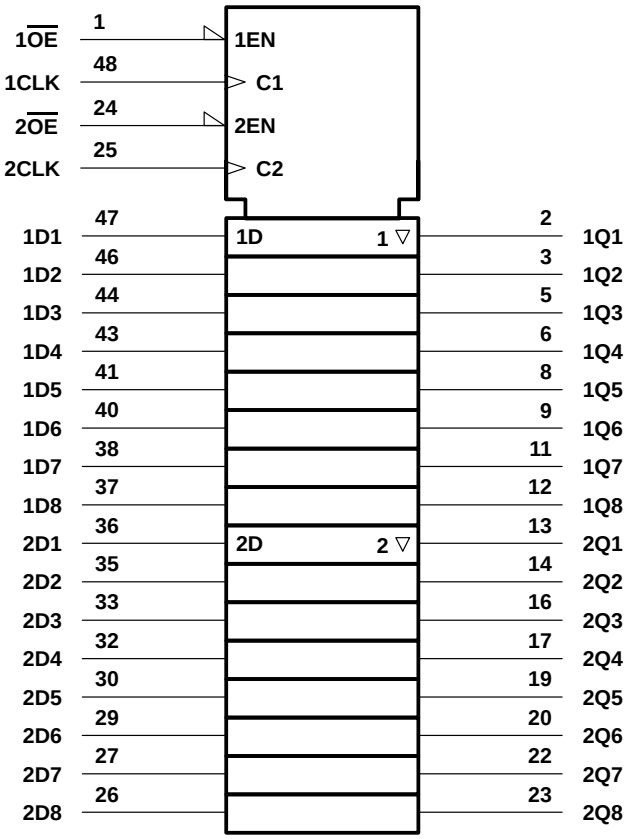
The 74AC16374 is packaged in TI’s shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16374 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74AC16374 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

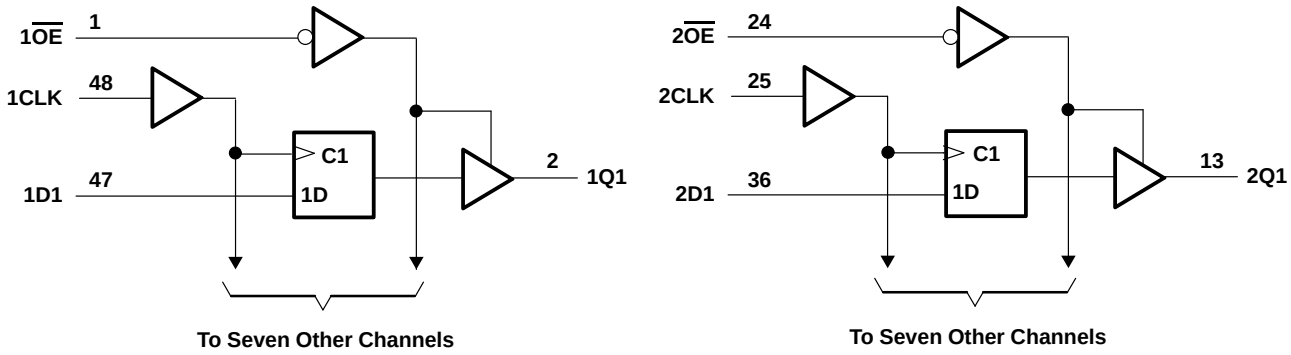
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	X	X	Q_0
L	↓	X	Q_0
H	X	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) . . . . . ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±400 mA
Maximum power package dissipation at T_A = 55°C (in still air)(see Note 2): DL package . . . . . 1.2 W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

			54AC16374			74AC16374			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4			–4	mA
		V_{CC} = 4.5 V			–24			–24	
		V_{CC} = 5.5 V			–24			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			54AC16374		74AC16374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = –4 mA	3 V	2.58			2.48		2.48		
	I_{OL} = –24 mA	4.5 V	3.94			3.8		3.8		
		5.5 V	4.94			4.8		4.8		
	I_{OH} = –75 mA†	5.5 V				3.85		3.85		
V_{OL}	I_{OL} = 50 μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.44		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65		1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	μA
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.5		±5		±5	μA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			8		80		80	μA
C_i	V_I = V_{CC} or GND	5 V		3						pF
C_o	V_O = V_{CC} or GND	5 V		11						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		54AC16374		74AC16374		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	60	0	60	0	60	MHz
t_w	Pulse duration	CLK high or low	8.3		8.3		8.3		ns
t_{su}	Setup time, data before CLK↑		7.5		7.5		7.5		ns
t_h	Hold time, data after CLK↑		0		0		0		ns

timing requirements over recommended operating free-air temperature range V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		54AC16374		74AC16374		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	100	0	100	0	100	MHz
t_w	Pulse duration	CLK high or low	5		5		5		ns
t_{su}	Setup time, data before CLK↑		5		5		5		ns
t_h	Hold time, data after CLK↑		0		0		0		ns

switching characteristics over recommended operating free-air temperature range V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16374		74AC16374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			60			60		60		MHz
t_{PLH}	CLK	Q	4.9	12.2	15	4.9	17	4.9	17	ns
t_{PHL}			4.8	11.9	14.3	4.8	15.7	4.8	15.7	
t_{PZH}	$\overline{OE}$	Q	4.3	11.9	14.7	4.3	16.8	4.3	16.8	ns
t_{PZL}			5.3	15.5	18.7	5.3	21.2	5.3	21.2	
t_{PHZ}	$\overline{OE}$	Q	4	7.3	9	4	9.8	4	9.8	ns
t_{PLZ}			3.8	7.1	8.8	3.8	9.4	3.8	9.4	

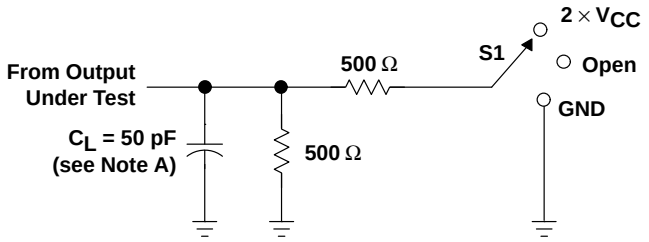
switching characteristics over recommended operating free-air temperature range V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16374		74AC16374		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			100			100		100		MHz
t_{PLH}	CLK	Q	3.8	7.6	9.5	3.8	10.8	3.8	10.8	ns
t_{PHL}			3.8	7.6	9.5	3.8	10.6	3.8	10.6	
t_{PZH}	$\overline{OE}$	Q	3.2	7.2	9	3.2	10.2	3.2	10.2	ns
t_{PZL}			3.8	8.7	10.7	3.8	12.1	3.8	12.1	
t_{PHZ}	$\overline{OE}$	Q	3.7	6	7.5	3.7	8.2	3.7	8.2	ns
t_{PLZ}			3.5	5.8	7.3	3.5	7.9	3.5	7.9	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

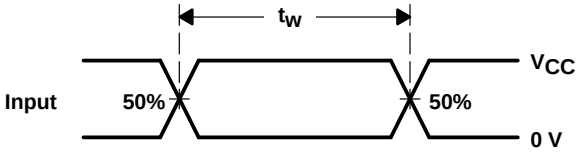
PARAMETER			TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance per flip-flop	Outputs enabled	C_L = 50 pF,	f = 1 MHz	49	pF
		Outputs disabled			32	

PARAMETER MEASUREMENT INFORMATION

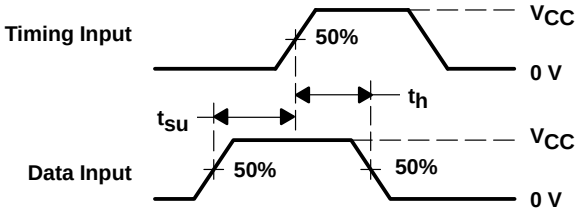


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT



VOLTAGE WAVEFORMS



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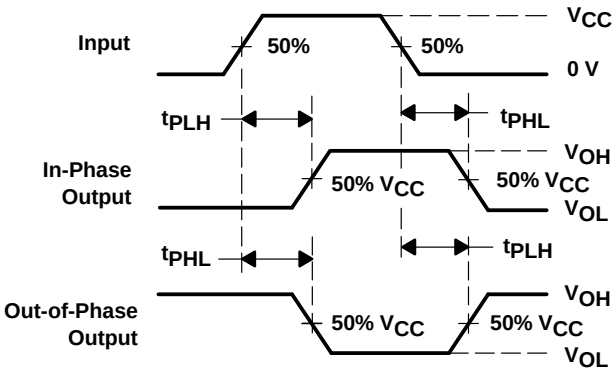
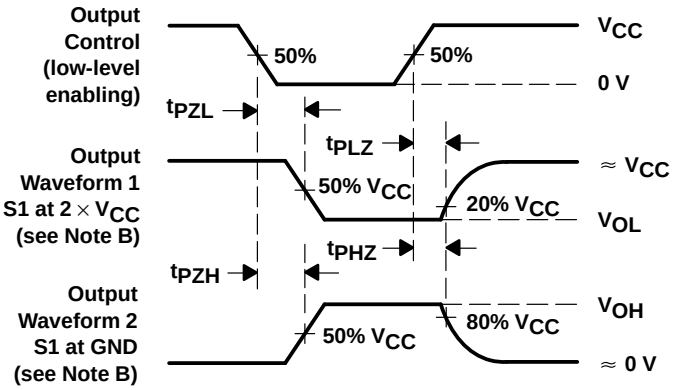


VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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